

# RV1S2955A

R08DS0289EJ0100

LOW FORWARD-CURRENT(I<sub>F</sub>), OPERATING AMBIENT TEMPERATURE 115 °C,  
4-PIN ULTRA SMALL PACKAGE FLAT-LEAD PHOTOCOUPLER

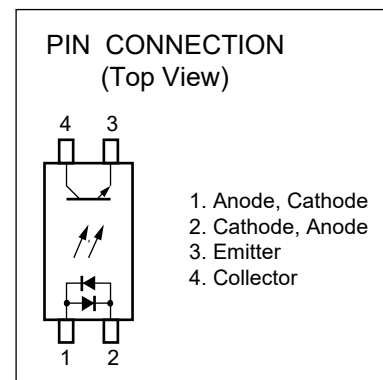
Rev.1.00  
Jun. 20, 2024

## DESCRIPTION

The RV1S2955A is an optically coupled transistor-output isolator featuring the high current transfer ratio at a sub-mA of the forward current. The RV1S2955A consists of two AlGaAs LEDs for AC input signal on the input side and an NPN silicon phototransistor on the output side in an ultra-small flat-lead package to reduce the mounting area by 30 % compared with the SSOP for PS28xx series keeping 4 mm creepage distance.

## FEATURES

- Ultra small flat-lead package (4.6 (W) × 2.5 (L) × 2.1 (H) mm)
- AC input response
- High current transfer ratio (CTR = 300 % MIN. @ I<sub>F</sub> = 50 μA)
- Operating ambient temperature (115 °C MAX.)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Embossed tape product:  
RV1S2955ACCNS-1F0x#KC0: 3 500 pcs/reel
- Pb-free product
- Safety standard
  - UL : UL1577, Single protection
  - CSA : CAN/CSA-C22.2 No.62368-1, Reinforced insulation
  - VDE : DIN EN IEC 60747-5-5 (Option)

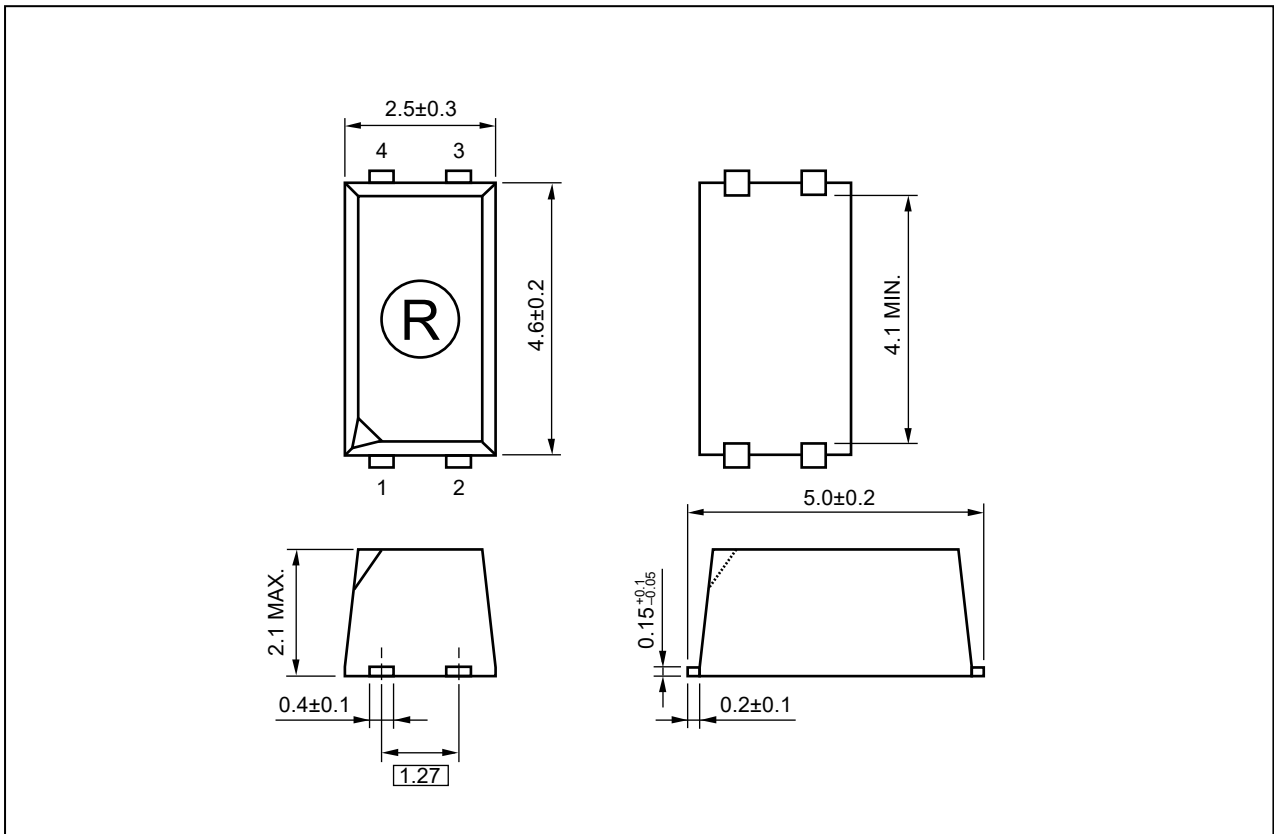


## APPLICATIONS

- Air conditioner
- Measurement equipment
- Power supply

Start of mass production  
Jul. 2024

PACKAGE DIMENSIONS (UNIT: mm)

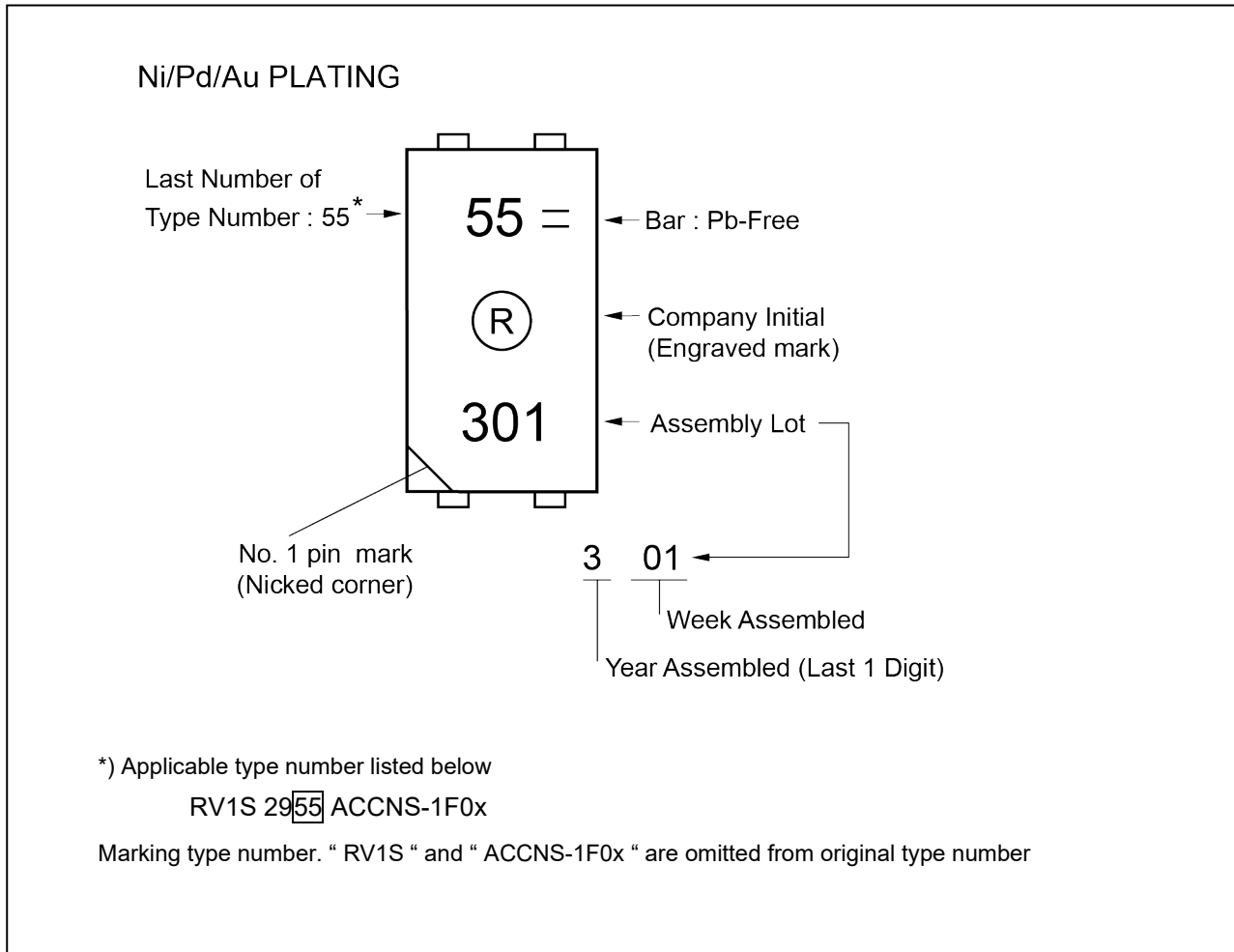


Weight : 0.05 g (TYP.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.15 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *1
RV1S2955ACCNS-1F0C	RV1S2955ACCNS-1F0C#SC0	Pb-Free (Ni/Pd/Au)	Embossed Tape 50 pcs	UL, CSA Approved	RV1S2955A
	RV1S2955ACCNS-1F0C#KC0		Embossed Tape 3 500 pcs/reel		
RV1S2955ACCNS-1F0V	RV1S2955ACCNS-1F0V#SC0		Embossed Tape 50 pcs	UL, CSA, VDE Approved	
	RV1S2955ACCNS-1F0V#KC0		Embossed Tape 3 500 pcs/reel		

Notes: \*1. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	±2.5	mA
	Power Dissipation	P <sub>D</sub>	3.5	mW
	Peak Forward Current *1	I <sub>FP</sub>	±1.0	A
Transistor	Collector to Emitter Voltage	V <sub>CEO</sub>	40	V
	Emitter to Collector Voltage	V <sub>ECO</sub>	6	V
	Collector Current	I <sub>C</sub>	80	mA
	Power Dissipation Derating *2	ΔP <sub>C</sub> /°C	1.5	mW/°C
	Power Dissipation	P <sub>C</sub>	150	mW
Isolation Voltage *3		BV	2 500	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	-40 to +115	°C
Storage Temperature		T <sub>stg</sub>	-40 to +125	°C

Notes: \*1. PW = 100 μs, duty cycle = 1 %.

\*2. Reduced at a rate of 1.5 mW/°C above T<sub>A</sub> = 80 °C.

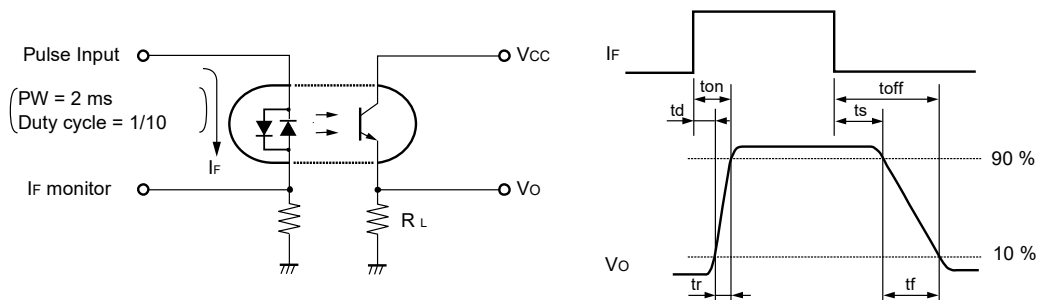
\*3. AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

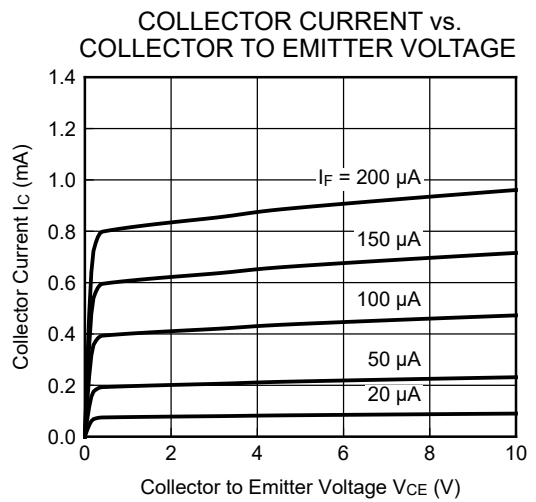
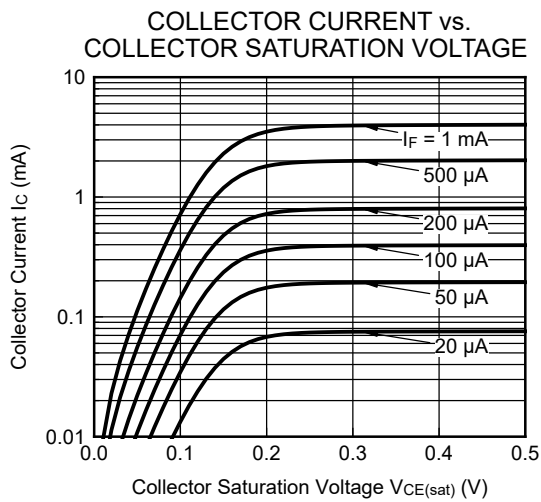
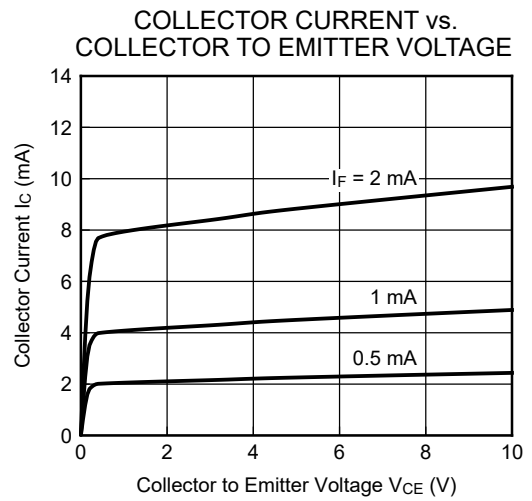
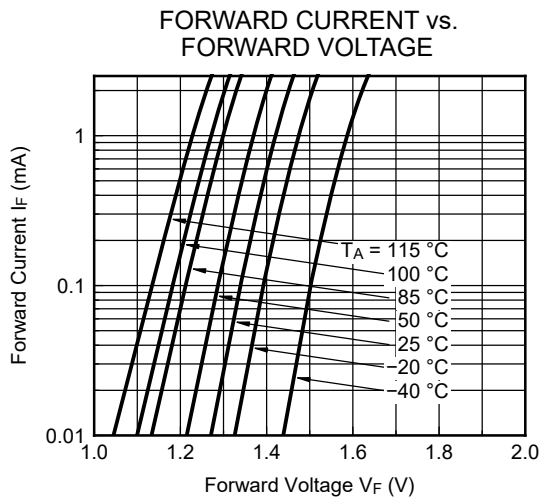
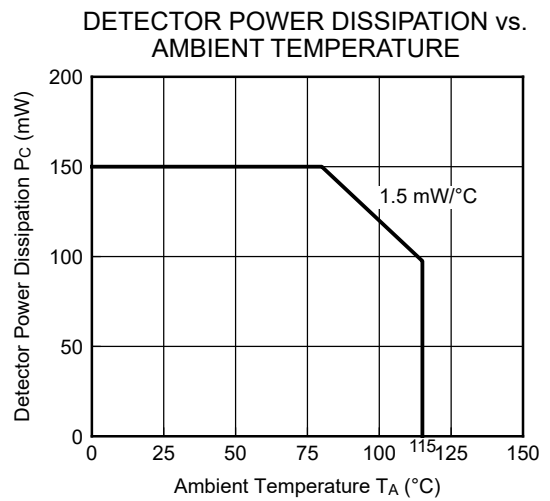
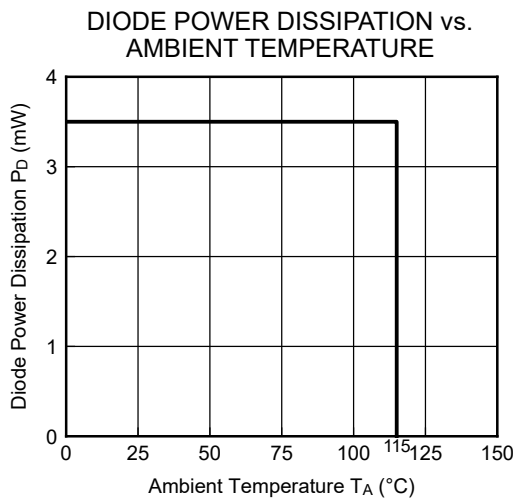
ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = ±0.1 mA	1.22	1.37	1.52	V
	Input Capacitance	C <sub>i</sub>	V = 0 V, f = 1 MHz		60		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 40 V			50	nA
Coupled	Current Transfer Ratio (I <sub>C</sub> /I <sub>F</sub> )	CTR1	I <sub>F</sub> = ±50 μA, V <sub>CE</sub> = 5 V	300		800	%
		CTR2	I <sub>F</sub> = ±1 mA, V <sub>CE</sub> = 5 V	300		800	%
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = ±0.1 mA, I <sub>C</sub> = 0.2 mA			0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time *1	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>F</sub> = ±0.1 mA, R <sub>L</sub> = 51 kΩ		115		μs
	Fall Time *1	t <sub>f</sub>			1 150		
	Turn-on Time *1	t <sub>on</sub>			130		
	Turn-off Time *1	t <sub>off</sub>			1 300		
	Rise Time *1	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>C</sub> = 2 mA, R <sub>L</sub> = 100 Ω		5		μs
Fall Time *1	t <sub>f</sub>			6			

Notes: \*1. Test circuit for switching time

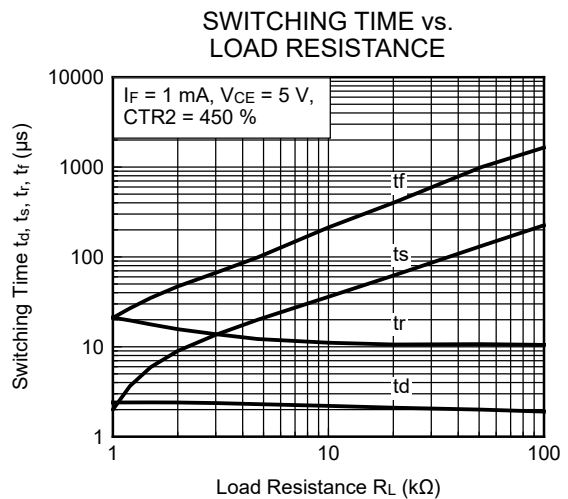
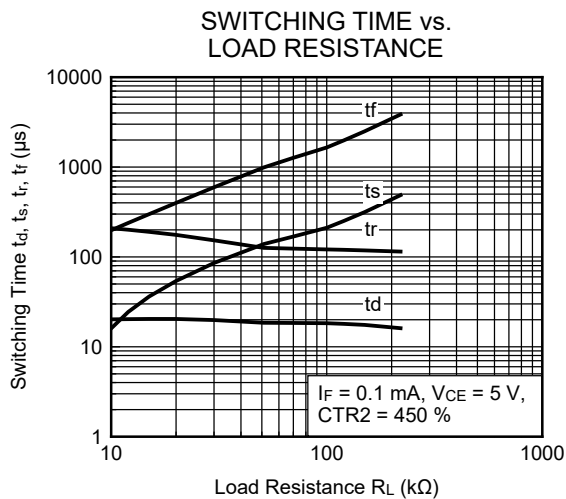
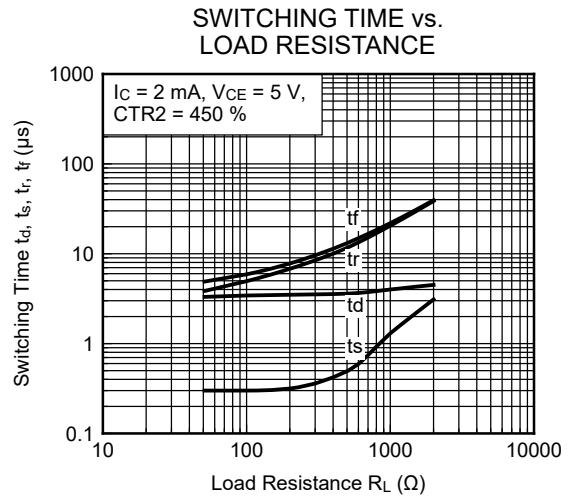
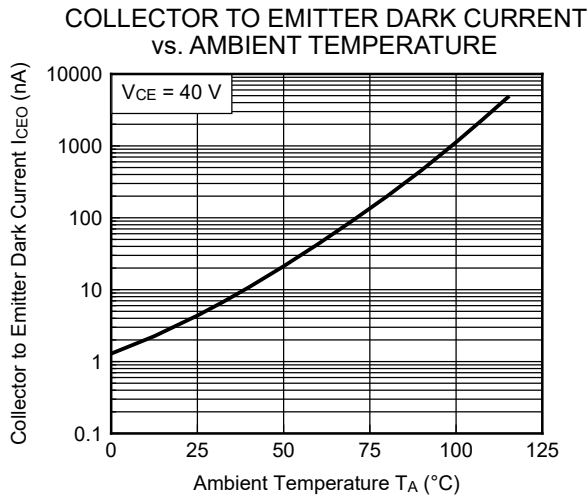
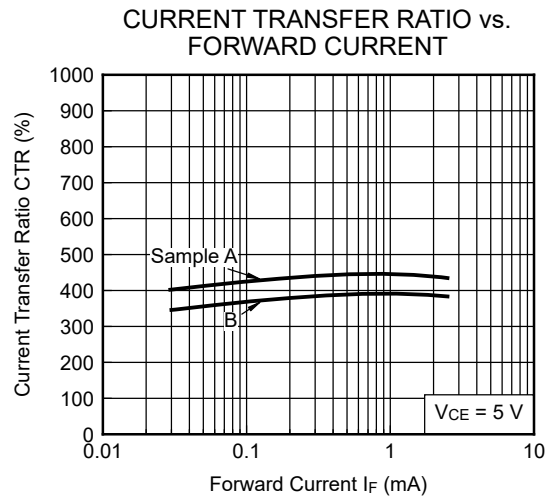
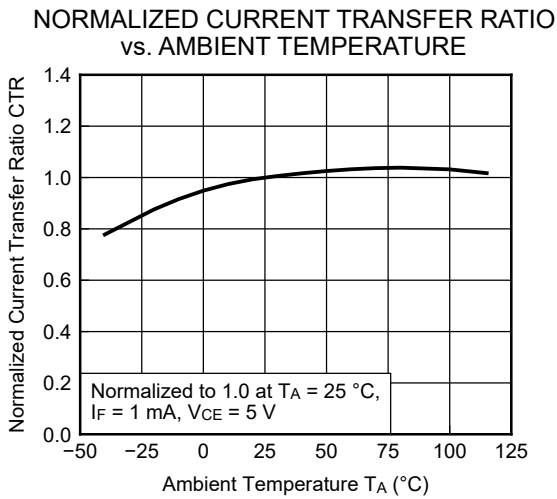


TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)



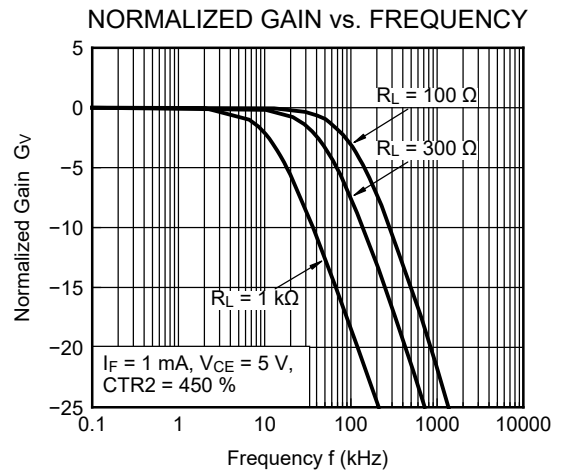
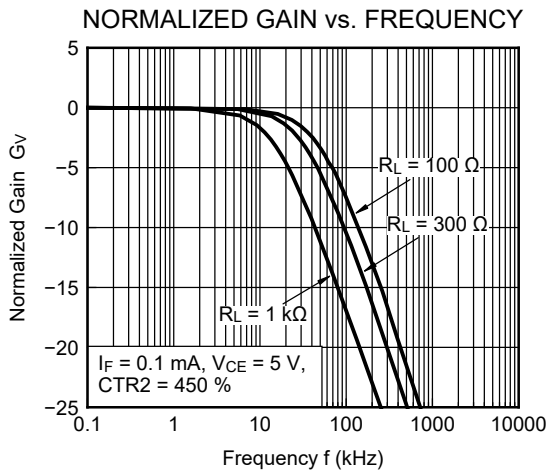
Remark The graphs indicate nominal characteristics.

TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)



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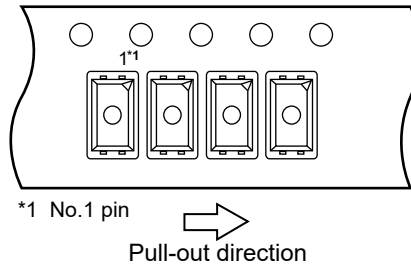
TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)



Remark The graphs indicate nominal characteristics.

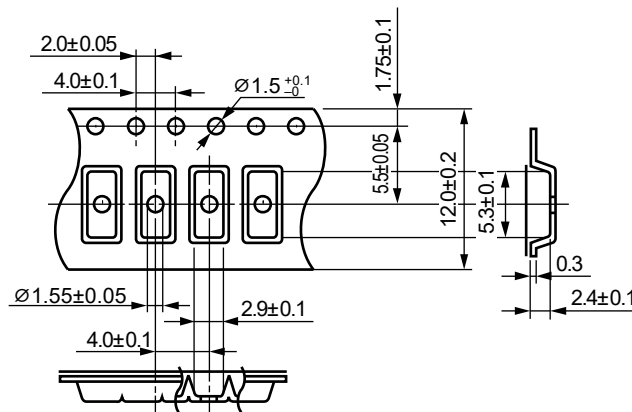
TAPING SPECIFICATIONS (UNIT: mm)

Tape Direction



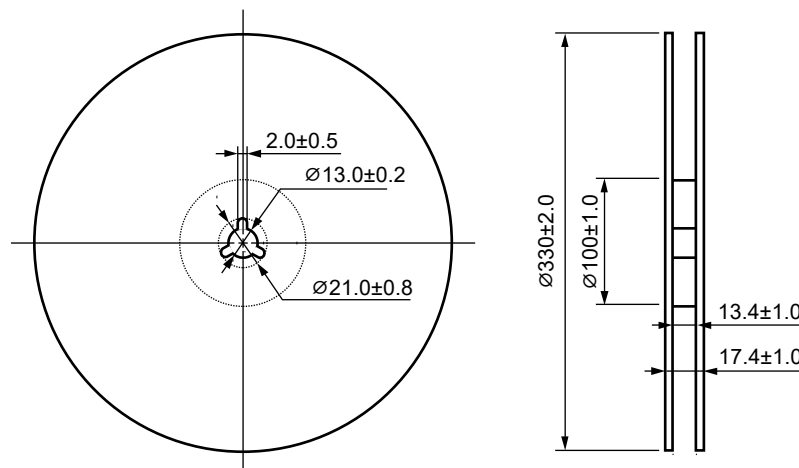
Outline and Dimensions (Tape)

(UNIT: mm)



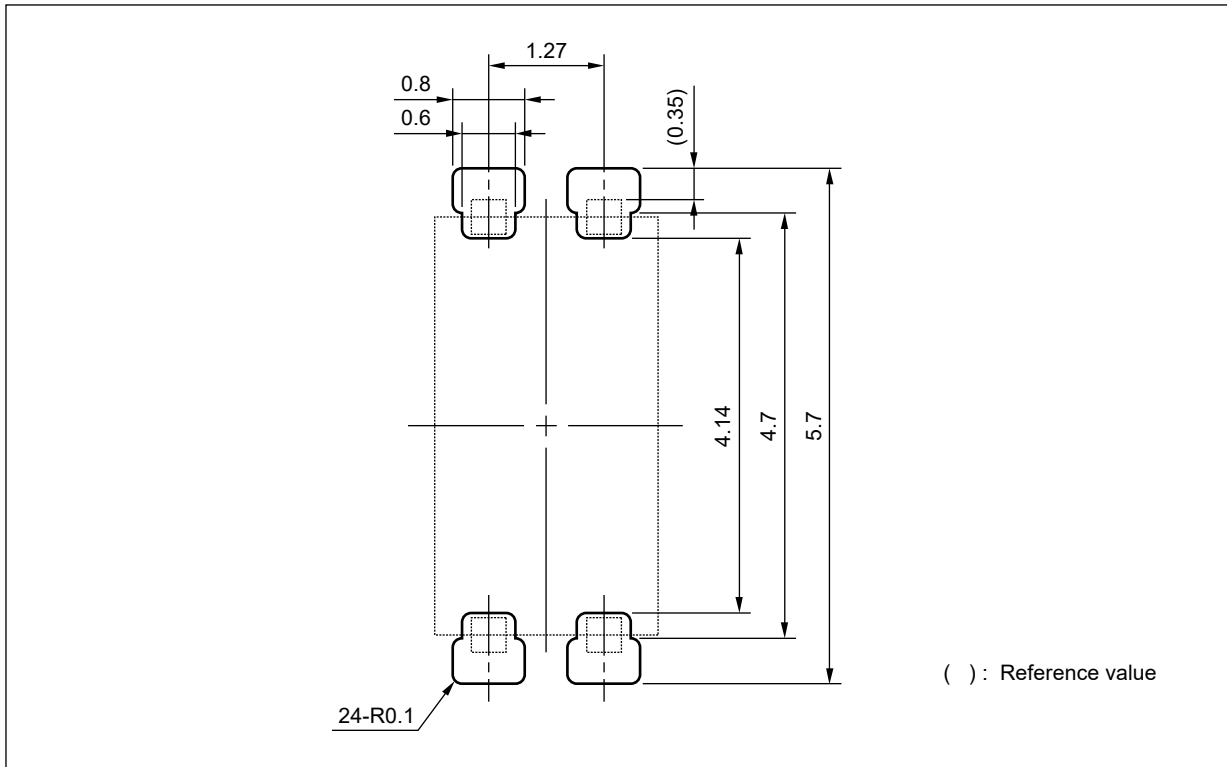
Outline and Dimensions (Reel)

(UNIT: mm)



Packing: 3 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.

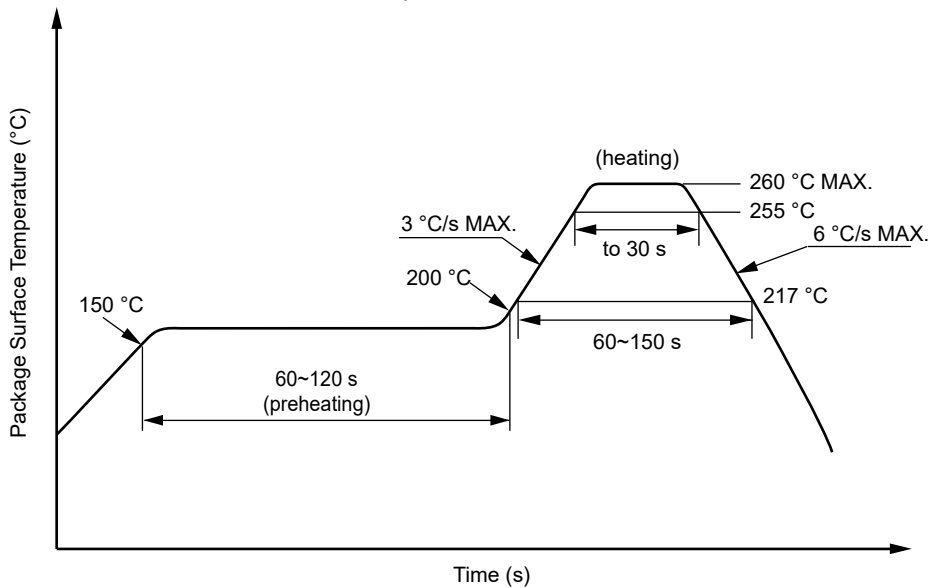
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260 °C or below (package surface temperature)
- Time of peak reflow temperature -5 °C (255 °C) 30 seconds or less
- Time of temperature higher than 217 °C 60 to 150 seconds
- Time to preheat temperature from 150 to 200 °C 60 to 120 seconds
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



JEDEC J-STD-020E compliant soldering conditions

(2) Wave soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120 °C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Flux cleaning Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents.
- Fixing/Coating Do not use fixing agents or coatings containing halogen-based substances

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler  
Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations of the like into consideration before use.

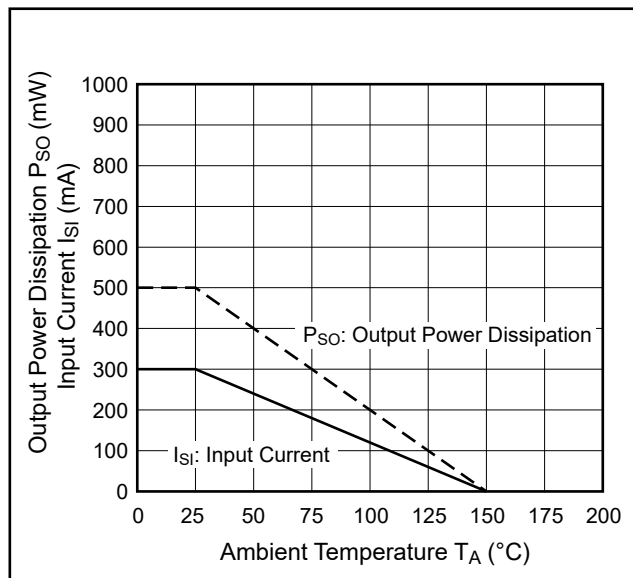
### USAGE CAUTIONS

1. Product against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

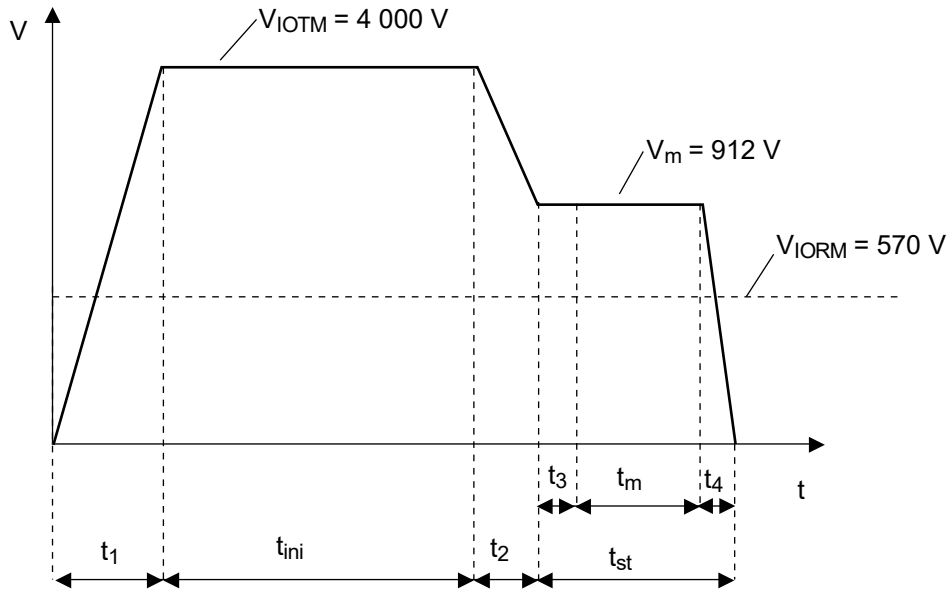
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/115/21	
Dielectric strength maximum operating isolation voltage	$V_{IORM}$	570	$V_{peak}$
Test voltage (partial discharge test, procedure a for type test and random test) $V_m = 1.6 \times V_{IORM}, q_{pd} < 5 \text{ pC}$	$V_m$	912	$V_{peak}$
Test voltage (partial discharge test, procedure b for all devices) $V_m = 1.875 \times V_{IORM}, q_{pd} < 5 \text{ pC}$	$V_m$	1 069	$V_{peak}$
Highest permissible overvoltage	$V_{IOTM}$	4 000	$V_{peak}$
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	$T_{stg}$	-40 to +125	°C
Operating temperature range	$T_A$	-40 to +115	°C
Isolation resistance, minimum value $V_{I-O} = 500 \text{ V dc}, T_A = 25 \text{ °C}$	$R_{I-O} \text{ MIN.}$	$10^{12}$	$\Omega$
$V_{I-O} = 500 \text{ V dc}, T_A = \text{maximum temperature of rating, at least } 100 \text{ °C}$	$R_{I-O} \text{ MIN.}$	$10^{11}$	$\Omega$
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Maximum ambient temperature	$T_s$	150	°C
Maximum input current	$I_{SI}$	300	mA
Maximum output power dissipation	$P_{SO}$	500	mW
Isolation resistance, minimum value at $V_{I-O} = 500 \text{ V dc}, T_A = T_s$	$R_{I-O} \text{ MIN.}$	$10^9$	$\Omega$

Dependence of maximum safety ratings on ambient temperature

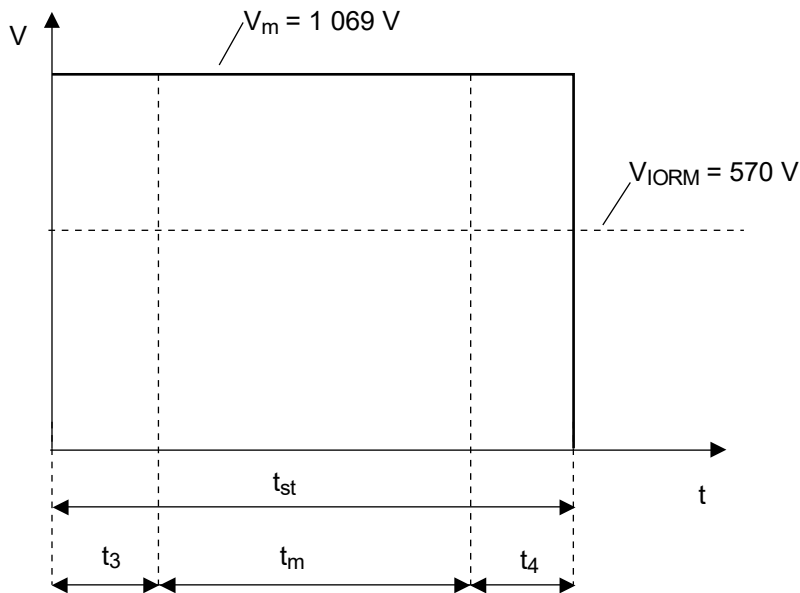


Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1 \text{ to } 10 \text{ sec}$   
 $t_3, t_4 = 1 \text{ sec}$   
 $t_m = 10 \text{ sec}$   
 $t_{st} = 12 \text{ sec}$   
 $t_{ini} = 60 \text{ sec}$

Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1 \text{ sec}$   
 $t_m = 1.0 \text{ sec}$   
 $t_{st} = 1.2 \text{ sec}$

<p><b>Caution</b> GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"><li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.<ol style="list-style-type: none"><li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li><li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol></li><li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li><li>• Do not lick the product or in any way allow it to enter the mouth.</li></ul>
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